AC220V±10% Power Supply BGA rework station supporting chip sizes 1×1mm to 70×70mm ideal for precise soldering and repair WDS-650

Our Product Introduction

Basic Information

- Brand Name: Wisdomshow
- Certification: CE
- Model Number: WDS-650
- Minimum Order Quantity: 1
- Packaging Details: Wooden Case
- Delivery Time: 3-5days
- Payment Terms: TT
- Supply Ability: 200Sets / Month



Product Specification

- Temperature Control: Closed-loop K-type Thermocouple, Upper & Lower Independent Heating, ±1°C Accuracy
- Applicable Chip Size: 1×1mm – 70×70mm
- Machine Weight: 0.02mm
- Chip Magnification: 2~32X
- Power Supply: AC220V±10%, 50/60Hz
- Max PCB Size: 480×380mm
- Total Power: 6800w
- Thermocouple Ports: 3pcs



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Product Description

Product Description:

The Semi Automatic BGA Rework Station is a highly advanced and reliable solution designed to meet the precise demands of modern electronic repair and manufacturing environments. Engineered with cutting-edge technology, this rework station offers exceptional performance for the removal, replacement, and reflow of Ball Grid Array (BGA) components. Its semi automatic operation, combined with an optical alignment system, ensures accuracy and efficiency, making it an indispensable tool for technicians and engineers working with complex printed circuit boards (PCBs).

One of the standout features of this Semi Automatic BGA Rework Station is its sophisticated temperature control system. Utilizing a closed-loop K-type thermocouple, the station delivers precise temperature regulation with an impressive accuracy of ±1°C. This level of control is critical when working with sensitive electronic components, as it minimizes the risk of thermal damage while ensuring optimal soldering conditions. The machine is equipped with both upper and lower independent heating zones, allowing for precise and even heat distribution. This dual heating capability enhances the reflow process by targeting the component and the PCB simultaneously, which results in superior solder joint quality.

Designed to accommodate a wide range of PCB sizes, this BGA rework station supports a maximum PCB dimension of 480×380mm. This flexibility makes it suitable for various applications, from small consumer electronics to larger industrial circuit boards. The machine's construction is both robust and lightweight, with a machine weight precision of 0.02mm, ensuring stability during operation while maintaining portability and ease of use.

The power supply requirements for the Semi Automatic BGA Rework Station are standardized to AC220V±10%, 50/60Hz, making it compatible with most laboratory and workshop power sources globally. This universal power compatibility ensures that users can operate the machine reliably without the need for additional adapters or converters, enhancing convenience and usability.

In addition to its precise temperature management and heating capabilities, the station features three thermocouple ports. These ports allow for comprehensive temperature monitoring at multiple points, providing critical feedback during the rework process. This multi-point temperature sensing capability contributes to the overall accuracy and effectiveness of the heating system, ensuring that the PCB and components are heated uniformly and safely.

A key advantage of this BGA rework station is its integration of a semi automatic optical alignment system. This system enhances the accuracy of component placement by providing real-time visual feedback, making the process faster and reducing the likelihood of errors. The optical alignment system is especially beneficial when dealing with fine-pitch BGA components, where precise positioning is crucial for successful rework outcomes.

The hot air heating mechanism is another vital aspect of this rework station. It provides controlled and uniform hot air flow, which is essential for the delicate process of solder melting and reflow. The hot air heating system works in conjunction with the independent upper and lower heaters to ensure efficient heat transfer, reducing the risk of PCB warping or component damage. This combination of heating technologies enhances the reliability and consistency of the rework process.

Overall, the Semi Automatic BGA Rework Station is an exceptional tool that combines precision temperature control, advanced optical alignment, and effective hot air heating to deliver consistent and high-quality rework results. Its design caters to the needs of professionals who demand accuracy, reliability, and efficiency in their electronic repair and assembly tasks. Whether used in a small repair shop or a large-scale manufacturing facility, this BGA rework station stands out as a premier choice for BGA component rework.

Features:

Product Name: Semi Automatic BGA Rework Station

Applicable Chip Size: 1×1mm – 70×70mm

Total Power: 6800w

Temperature Control: Closed-loop K-type Thermocouple with Upper & Lower Independent Heating and ±1°C Accuracy

Machine Weight: 0.02mm

Thermocouple Ports: 3pcs

Equipped with an Infrared preheating table for efficient and uniform heating

Designed for precise motherboard repair

Features an advanced optical alignment system for accurate chip placement

Technical Parameters:

Chip Magnification	2~32X
Applicable Chip Size	1×1mm – 70×70mm
Temperature Control	Closed-loop K-type Thermocouple, Upper & Lower Independent Heating, ±1°C Accuracy
Machine Weight	0.02mm
Thermocouple Ports	3pcs
Total Power	6800w
Max PCB Size	480×380mm
Power Supply	AC220V±10%, 50/60Hz

Applications:

The Wisdomshow WDS-650 Semi Automatic BGA Rework Station is an advanced and reliable tool designed specifically for precision

motherboard repair and cpu repair tasks. Manufactured in Shenzhen, China, this high-quality rework station is CE certified, ensuring compliance with international safety and performance standards. Ideal for electronics repair professionals and technicians, the WDS-650 offers exceptional temperature control with a closed-loop K-type thermocouple system, providing independent upper and lower heating with ±1°C accuracy. This feature guarantees precise thermal management essential for sensitive components such as CPUs and BGA chips during rework processes.

With a total power of 6800W and a power supply of AC220V±10%, 50/60Hz, the WDS-650 delivers consistent and efficient heating performance. It is equipped with three thermocouple ports that allow for accurate monitoring of multiple temperature points simultaneously, enhancing the reliability of motherboard repair and cpu repair operations. The chip magnification capability ranges from 2x to 32x, enabling detailed inspection and precise alignment of BGA components, which is crucial in semi automatic rework procedures where accuracy and control are paramount.

Packaging is carefully managed with a sturdy wooden case to ensure safe delivery, and the product is available with a minimum order quantity of just one set, making it accessible for both individual technicians and repair shops. With a supply ability of 200 sets per month and a delivery time of only 3-5 days, the Wisdomshow WDS-650 meets the demands of busy repair environments requiring quick turnaround times. Payment terms are flexible with TT accepted, facilitating smooth transactions.

The semi automatic nature of the WDS-650 BGA Rework Station streamlines the rework process by combining manual precision with automated heating and temperature control, making it a perfect choice for professional motherboard repair and cpu repair scenarios. Whether used in electronics repair centers, manufacturing quality control, or refurbishment workshops, this rework station excels in delivering consistent, high-quality results for complex BGA and CPU components.

Shenzhen Wisdomshow Technology Co.,ltd

+86 18926538696 elysia.li@wdsbga.cn bgaxraymachine.com

No. 3 Kangtai 3rd Road, Shatou Community, Shajing Street, Bao'an District, Shenzhen, China